

Polar™ HiPerFET™ **Power MOSFET**

IXFB300N10P

N-Channel Enhancement Mode Avalanche Rated Fast Intrinsic Diode

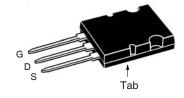


V _{DSS}	=	100V
D25	=	300A
R _{DS(on)}	≤	$5.5 \text{m}\Omega$
t _{rr}	≤	200ns

Symbol	Test Conditions	Maximum Ratings			
V _{DSS}	T _, = 25°C to 175°C	100	V		
V _{DGR}	$T_J^{\circ} = 25^{\circ}\text{C to } 175^{\circ}\text{C}, R_{gs} = 1\text{M}\Omega$	100	V		
V _{GSS}	Continuous	±20	V		
V _{GSM}	Transient	±30	V		
I _{D25}	T _C = 25°C	300	Α		
ILRMS	Leads Current Limit, RMS	160	Α		
I _{DM}	$T_{c} = 25^{\circ}C$, Pulse Width Limited by T_{JM}	900	Α		
I _A	T _C = 25°C	100	A		
É _{AS}	$T_{C}^{\circ} = 25^{\circ}C$	3	J		
dv/dt	$I_{_{S}} \le I_{_{DM}}, V_{_{DD}} \le V_{_{DSS}}, T_{_{J}} \le 175^{\circ}C$	20	V/ns		
P _D	T _C = 25°C	1500	W		
T _J		-55 +175	°C		
T _{JM}		175	°C		
T _{stg}		-55 +175	°C		
T _L	Maximum Lead Temperature for Soldering	300	°C		
T _{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C		
F _c	Mounting Force	30120/6.727	N/lb		
Weight		10	g		

Symbol	Test Conditions			ic Values		
$(T_J = 25^{\circ}C,$	Unless Otherwise Specified)		Min.	Тур.	Max.	
BV _{DSS}	$V_{GS} = 0V, I_{D} = 3mA$		100			V
V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 8mA$		2.5		5.0	V
GSS	$V_{GS} = \pm 20V, V_{DS} = 0V$				±200	nA
I _{DSS}	$V_{DS} = V_{DSS}, V_{GS} = 0V$				25	μΑ
		$T_J = 150^{\circ}C$			1.5	mA
R _{DS(on)}	$V_{GS} = 10V, I_{D} = 50A, Note 1$				5.5	mΩ

PLUS264™



$$G = Gate$$
 $D = Drain$ $S = Source$ $Tab = Drain$

Features

- Low R_{DS(on)} and Q_G
 Avalanche Rated
- Low Package Inductance
- Fast Intrinsic Diode

Advantages

- High Power Density
- Easy to Mount
- Space Savings

Applications

- DC-DC Coverters
- Battery Chargers
- Switch-Mode and Resonant-Mode **Power Supplies**
- DC Choppers
- AC and DC Motor Drives
- Uninterrupted Power Supplies
- High Speed Power Switching Applications





•		Chara	acteristic Values			
$(T_J = 25^{\circ}C, L)$	Inless Otherwise Specified)	Min.	Тур.	Max	.	
g _{fs}	$V_{DS} = 10V, I_{D} = 60A, Note 1$	55	92		S	
C _{iss}			23		nF	
C _{oss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		6100		pF	
C _{rss}			417		pF	
t _{d(on)}	Resistive Switching Times		36		ns	
t,	$V_{GS} = 10V$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_{D} = 100A$		35		ns	
t _{d(off)}	$R_{\rm g} = 10$ (External)		56		ns	
t _f	G . , ,		25		ns	
$\mathbf{Q}_{g(on)}$			279		nC	
Q _{gs}	$V_{GS} = 10V$, $V_{DS} = 0.5 \cdot V_{DSS}$, $I_{D} = 0.5 \cdot I_{D25}$		84		nC	
\mathbf{Q}_{gd}			107		nC	
\mathbf{R}_{thJC}				0.10	°C/W	
R _{thCS}			0.13		°C/W	

PLUS264TM (IXFB) Outline BACK SIDE 1 - Gate 2,4 - Drain 3 - Source

MYZ	INCHES		MILLIMETERS		
2114	MIN	MAX	MIN	MAX	
Α	.185	.209	4.70	5.31	
A1	.102	.118	2.59	3.00	
b	.037	.055	0.94	1.40	
Ь1	.087	.102	2.21	2.59	
b2	.110	.126	2.79	3.20	
С	.017	.029	0.43	0.74	
D	1.007	1.047	25,58	26,59	
Е	.760	.799	19,30	20.29	
е	.215	BSC	5.46 BSC		
L	.779	.842	19.79	21.39	
L1	.087	.102	2.21	2.59	
Q	.240	.256	6.10	6.50	
Q1	.330	.346	8.38	8.79	
ØR	.155	.187	3.94	4.75	
ØR1	.085	.093	2.16	2.36	

Source-Drain Diode

Symbol	Symbol Test Conditions Characteristic Value			Values	
$(T_J = 25^{\circ}C,$	Unless Otherwise Specified)	Min.	Тур.	Max.	
I _s	$V_{GS} = 0V$			300	Α
SM	Repetitive, Pulse Width Limited by $T_{_{\rm JM}}$			1000	Α
V _{SD}	$I_F = 100A$, $V_{GS} = 0V$, Note 1			1.3	V
t _{rr} Q _{RM} I _{RM}	$\begin{cases} I_{F} = 150A, -di/dt = 100A/\mu s \\ V_{R} = 50V \end{cases}$		0.71 10	200	ns μC A

Note 1: Pulse test, $t \le 300 \mu s$, duty cycle, $d \le 2\%$.



Fig. 1. Extended Output Characteristics @ T_J = 25°C

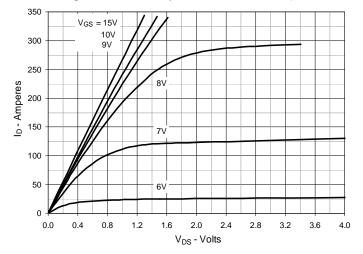


Fig. 2. Output Characteristics @ T_J = 150°C

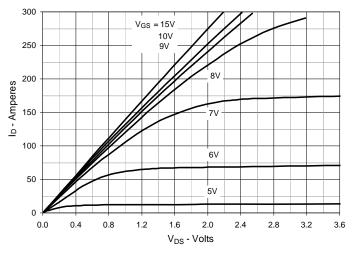


Fig. 3. $R_{DS(on)}$ Normalized to I_D = 150A Value vs.

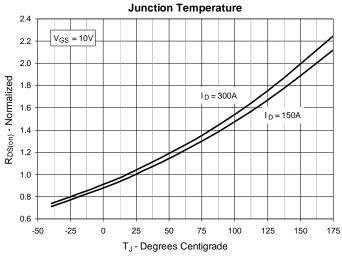


Fig. 4. $R_{DS(on)}$ Normalized to I_D = 150A Value vs.

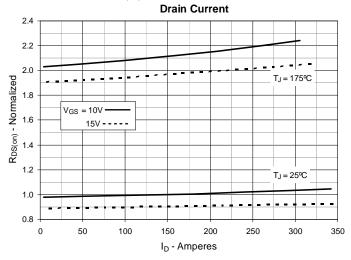
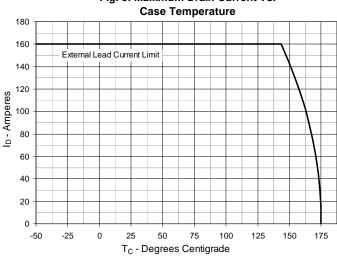
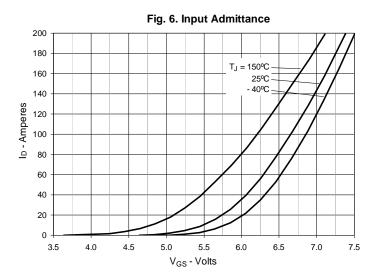


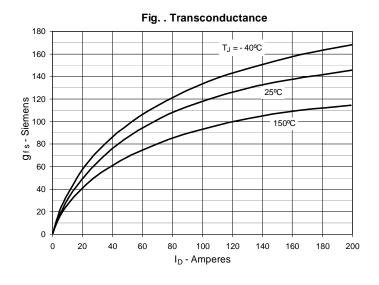
Fig. 5. Maximum Drain Current vs.

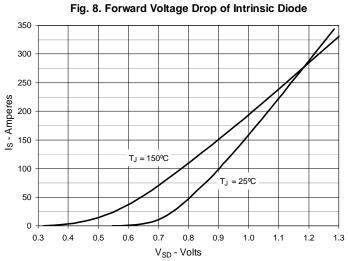


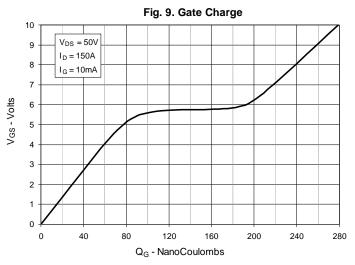


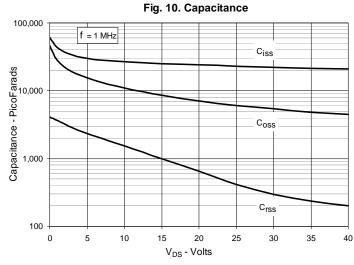
IXFB300N10P

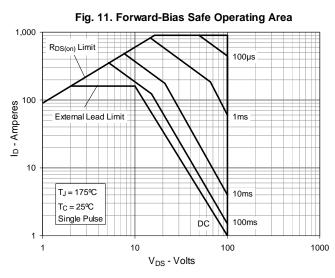


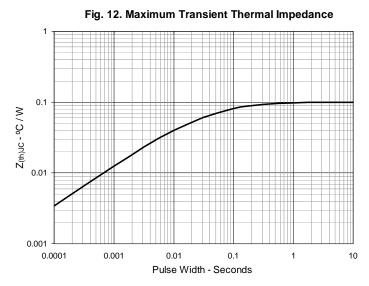












IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

